

IN THE CLAIMS:

Claims 1-3, and 5-22 have been amended herein. All of the pending claims 1 through 22 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A semiconductor device assembly, comprising:
 - a first semiconductor device including a surface with a plurality of peripherally located bond pads;
 - a rerouting element positioned over ~~said the~~ first semiconductor device, ~~said the~~ rerouting element comprising:
 - a base substrate;
 - a plurality of conductive vias positioned adjacent at least two peripheral edges of ~~said the~~ base substrate, each conductive via of ~~said the~~ plurality of conductive vias being located so as to align with a corresponding, peripherally located bond pad of the first semiconductor device upon assembly of ~~said the~~ rerouting element with the first semiconductor device;
 - a plurality of conductive traces; and
 - a plurality of rerouted bond pads, each conductive trace of ~~said the~~ plurality of conductive traces extending from a corresponding conductive via of the plurality of conductive vias toward at least one other peripheral edge of ~~said the~~ base substrate to a corresponding rerouted bond pad of ~~said the~~ plurality of rerouted bond pads; and
 - a second semiconductor device positioned over a portion of ~~said the~~ rerouting element, each of ~~said the~~ plurality of rerouted bond pads being exposed beyond a periphery of ~~said the~~ rerouting element.

2. (Currently Amended) The semiconductor device assembly of claim 1, wherein each rerouted bond pad of said the plurality of rerouted bond pads is located laterally adjacent a periphery of said the first semiconductor device.

3. (Currently Amended) The semiconductor device assembly of claim 1, wherein each rerouted bond pad of said the plurality of rerouted bond pads is located adjacent a single edge of said the first semiconductor device.

4. (Original) The semiconductor device assembly of claim 1, further comprising: a carrier substrate.

5. (Currently Amended) The semiconductor device assembly of claim 4, wherein said the first semiconductor device is secured to said the carrier substrate.

6. (Currently Amended) The semiconductor device assembly of claim 4, wherein said the carrier substrate comprises at least one of a circuit board, an interposer, another semiconductor device, and leads.

7. (Currently Amended) The semiconductor device assembly of claim 4, wherein said the at least one rerouted bond pad is in communication with a corresponding contact area of said the carrier substrate.

8. (Currently Amended) The semiconductor device assembly of claim 7, further comprising:
a discrete conductive element positioned between said the at least one rerouted bond pad and said the corresponding contact area.

9. (Currently Amended) The semiconductor device assembly of claim 8, wherein ~~said the at least one~~ discrete conductive element comprises at least one of a bond wire, a tape-automated bond element trace, and a lead.

10. (Currently Amended) The semiconductor device assembly of claim 1, further comprising:

another rerouting element on a bond pad-bearing surface of ~~said the~~ second semiconductor device.

11. (Currently Amended) The semiconductor device assembly of claim 1, wherein ~~said the~~ second semiconductor device is oriented in staggered relation to ~~said the~~ first semiconductor device.

12. (Currently Amended) The semiconductor device assembly of claim 1, wherein ~~said the~~ second semiconductor device is smaller than ~~said the~~ first semiconductor device.

13. (Currently Amended) The semiconductor device assembly of claim 1, further comprising:

at least one additional semiconductor device positioned over ~~said the~~ second semiconductor device.

14. (Currently Amended) The semiconductor device assembly of claim 8, further comprising:

an encapsulant protecting at least portions of ~~said the~~ first semiconductor device, ~~said the~~ second semiconductor device, ~~said the at least one~~ discrete conductive element, and portions of ~~said the~~ carrier substrate located laterally adjacent outer peripheries of ~~said the~~ first and second semiconductor devices.

15. (Currently Amended) The semiconductor device assembly of claim 14, wherein said the encapsulant comprises a glob-top type encapsulant.

16. (Currently Amended) The semiconductor device assembly of claim 14, wherein said the encapsulant comprises a transfer molding compound.

17. (Currently Amended) The semiconductor device assembly of claim 14, further comprising:

at least one external connective element in communication with at least one bond pad of said the first semiconductor device.

18. (Currently Amended) A rerouting element for use with a semiconductor device, comprising:

a base substrate;

a plurality of conductive vias positioned adjacent at least two peripheral edges of said the base substrate, each conductive via of said the plurality of conductive vias being located so as to align with a corresponding, peripherally located bond pad of the semiconductor device upon assembly of said the rerouting element with the semiconductor device;

a plurality of conductive traces; and

a plurality of contact pads, each conductive trace of said the plurality of conductive traces extending from a corresponding conductive via toward at least one other peripheral edge of said the base substrate to a corresponding contact pad of said the plurality of contact pads.

19. (Currently Amended) The rerouting element of claim 18, wherein said the plurality of conductive vias are positioned adjacent three peripheral edges of said the base substrate.

20. (Currently Amended) The rerouting element of claim 19, wherein each contact pad of ~~said~~ the plurality of contact pads is positioned adjacent to another, single peripheral edge of ~~said~~ the base substrate.

21. (Currently Amended) The rerouting element of claim 18, wherein ~~said~~ the plurality of conductive vias are positioned adjacent to two adjacent peripheral edges of ~~said~~ the base substrate.

22. (Currently Amended) The rerouting element of claim 21, wherein each contact pad of ~~said~~ the plurality of contact pads is positioned adjacent to at least one of two other adjacent peripheral edges of ~~said~~ the base substrate.